

Hyperfast Rectifier, 5 A FRED Pt®


SMC (DO-214AB)


FEATURES

- Hyperfast recovery time, reduced Q_{rr} and soft recovery
- 175 °C maximum operating junction temperature
- For PFC CRM/CCM, snubber operation
- Low forward voltage drop
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS

$I_{F(AV)}$	5 A
V_R	600 V
V_F at I_F	1.2 V
t_{rr} typ.	30 ns
T_J max.	175 °C
Package	SMC (DO-214AB)
Circuit configuration	Single

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC Boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

MECHANICAL DATA

Case: SMC (DO-214AB)

Molding compound meets UL 94 V-0 flammability rating
Halogen-free, RoHS-compliant

Terminals: matte tin plated leads, solderable per J-STD-002

Polarity: color band denotes cathode end

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current	$I_{F(AV)}$	$T_L = 73\text{ °C}^{(1)}$	5	A
Non-repetitive peak surge current	I_{FSM}	$T_J = 25\text{ °C}$, 10 ms sine pulse	110	
Operating junction and storage temperatures	T_J, T_{Stg}		-55 to +175	°C

Note

⁽¹⁾ Mounted on PCB with minimum pad size

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage	V_F	$I_F = 5\text{ A}$	-	1.65	1.95	
		$I_F = 5\text{ A}$, $T_J = 150\text{ °C}$	-	1.2	1.4	
Reverse leakage current	I_R	$V_R = V_R$ rated	-	-	3	μA
		$T_J = 150\text{ °C}$, $V_R = V_R$ rated	-	-	100	
Junction capacitance	C_T	$V_R = 600\text{ V}$	-	7.8	-	pF

DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1.0\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	30	-	ns
		$I_F = 1.0\text{ A}$, $di_F/dt = 50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	35	-	
		$I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$	-	-	35	
		$T_J = 25\text{ }^{\circ}\text{C}$	-	23	-	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	38	-	
Peak recovery current	I_{RRM}	$T_J = 25\text{ }^{\circ}\text{C}$	-	3.5	-	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	5.4	-	
Reverse recovery charge	Q_{rr}	$T_J = 25\text{ }^{\circ}\text{C}$	-	41	-	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	111	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C
Thermal resistance, junction to mount	R _{thJM} ⁽¹⁾		-	-	14	°C/W
Thermal resistance, junction to ambient	R _{thJA} ⁽¹⁾		-	-	80	
Approximate Weight			0.24			g
			0.008			oz.
Marking device		Case style SMC (DO-214AB)	5H6			

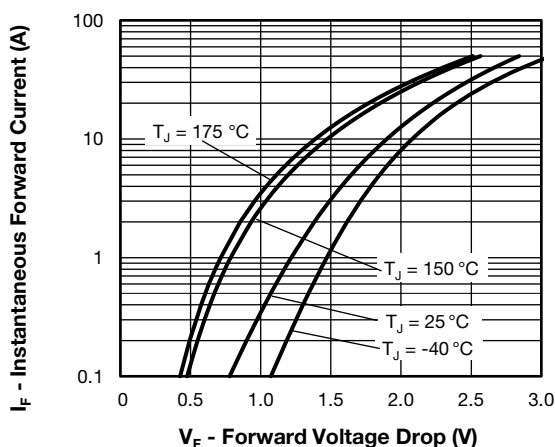
Note
⁽¹⁾ Mounted on PCB with minimum pad size


Fig. 1 - Typical Forward Voltage Drop Characteristics

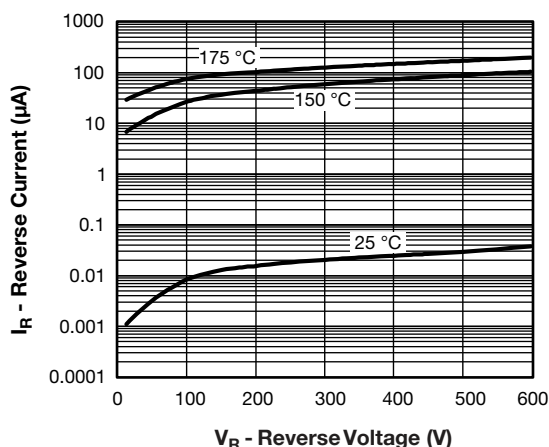


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

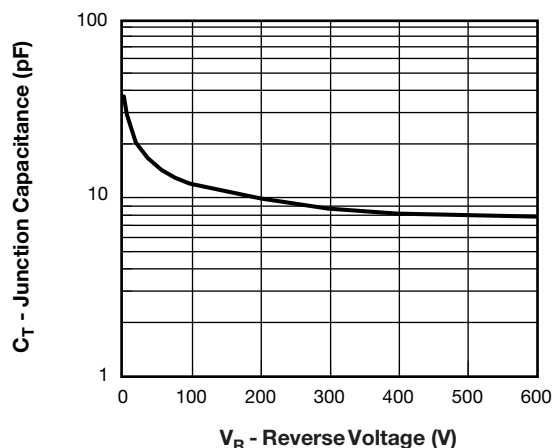


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

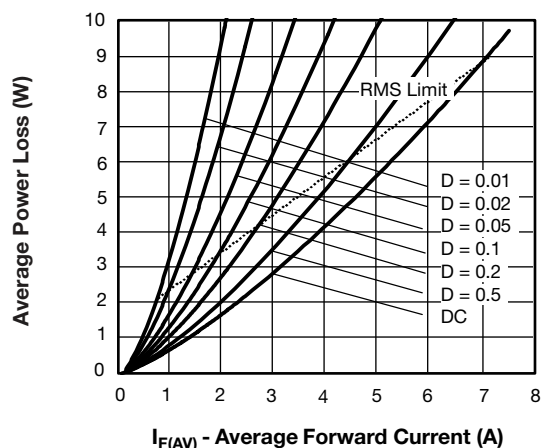


Fig. 5 - Forward Power Loss Characteristics

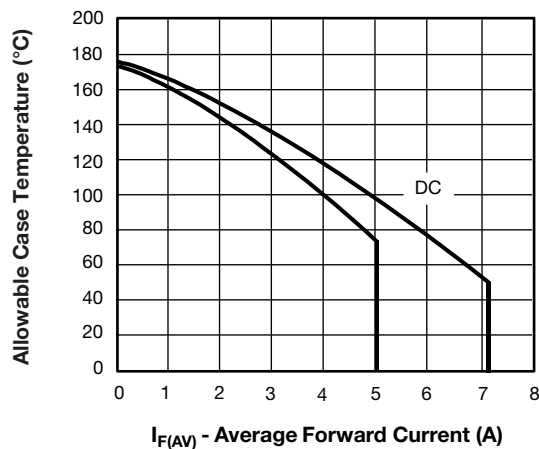


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current

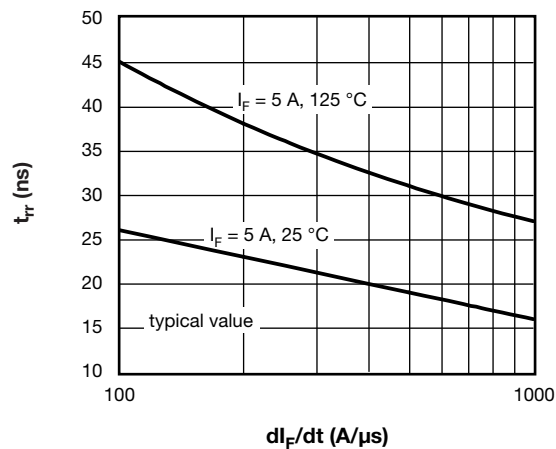


Fig. 6 - Typical Reverse Recovery vs. di_F/dt

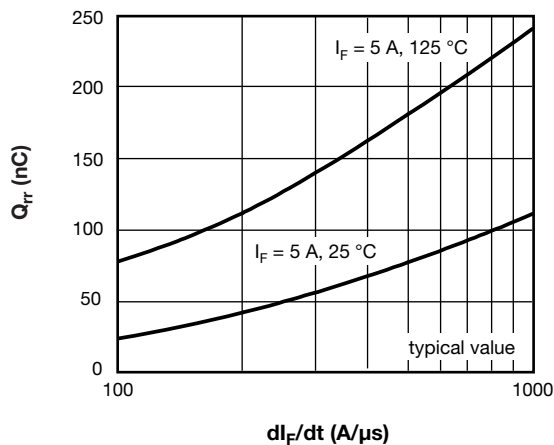


Fig. 7 - Typical Stored Charge vs. di_F/dt

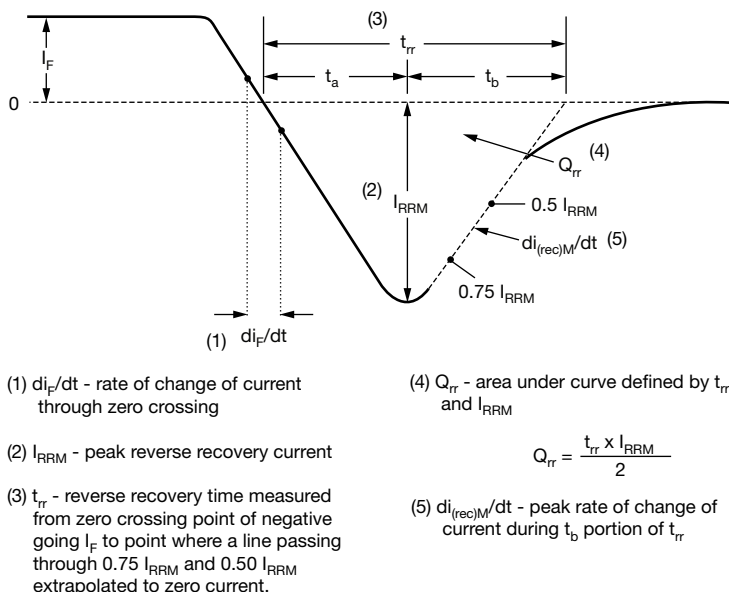


Fig. 8 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code	VS-	5	E	C	H	06	-M3
	1	2	3	4	5	6	7

- 1** - Vishay Semiconductors product
- 2** - Current rating (5 = 5 A)
- 3** - Circuit configuration:
E = single diode
- 4** - C = SMC package
- 5** - Process type,
H = hyperfast recovery
- 6** - Voltage code (06 = 600 V)
- 7** - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)

PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-5ECH06-M3/9AT	9AT	3500	13" diameter plastic tape and reel

LINKS TO RELATED DOCUMENTS

Dimensions	www.vishay.com/doc?95402
Part marking information	www.vishay.com/doc?95472
Packaging information	www.vishay.com/doc?95404
SPICE model	www.vishay.com/doc?96709

SMC

DIMENSIONS in inches (millimeters)





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